

(a) Base layer deposition

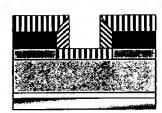


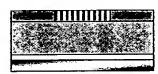
base layer (e.g., silicon nitride) deposited (e.g.,a-Si or poly Si) optimal etch stop or barrier layer substrate

(b) Lithography and base layer etching



(c) Sacrificial layer deposition





ta) Lift-off



(e) Capping layer deposition

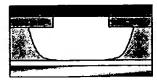


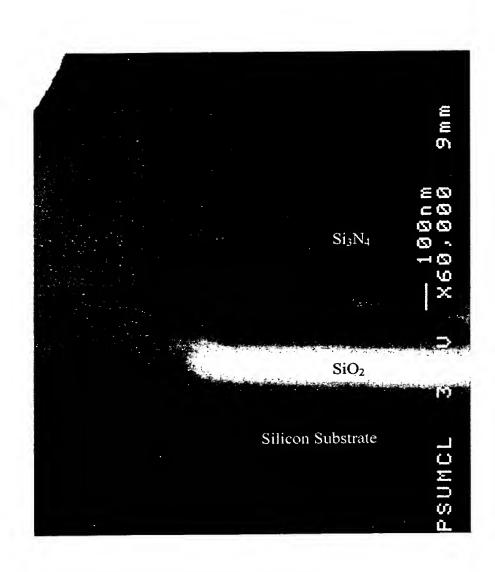
(f) Etchant access window etching

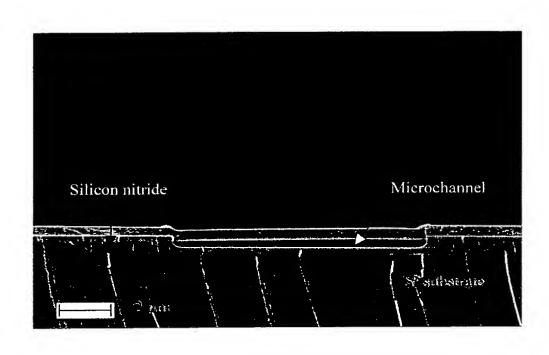
(g) Sacrificial layer etching and trench creation

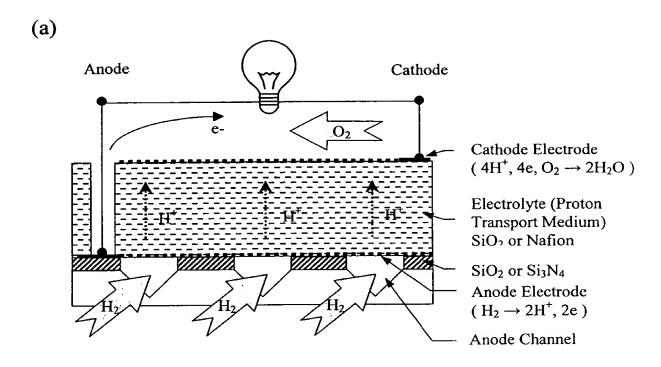


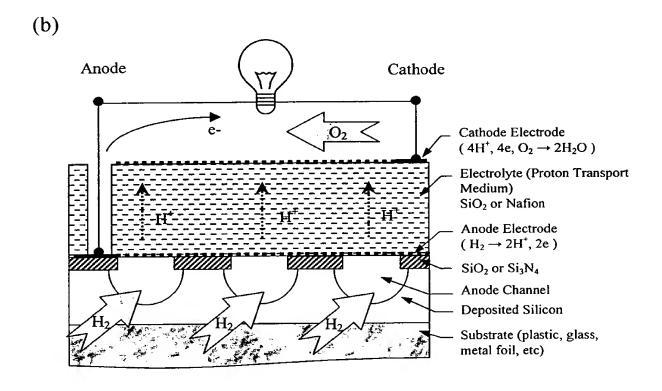
(h) Window filling



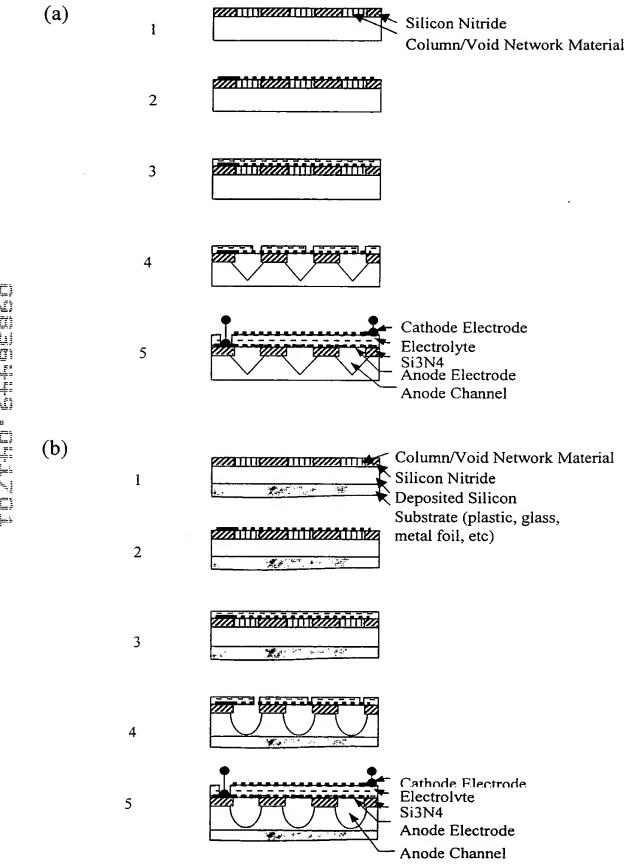


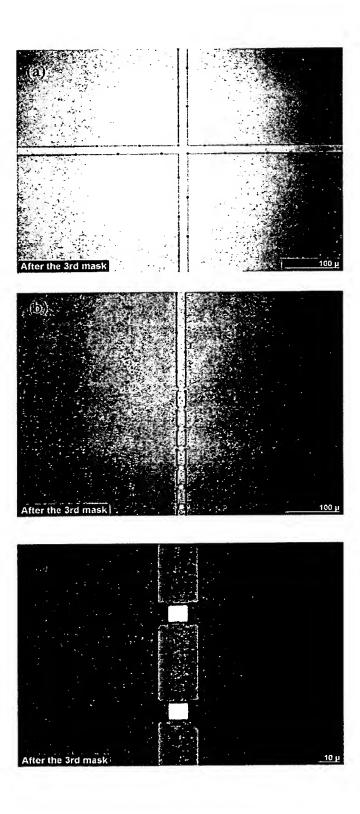




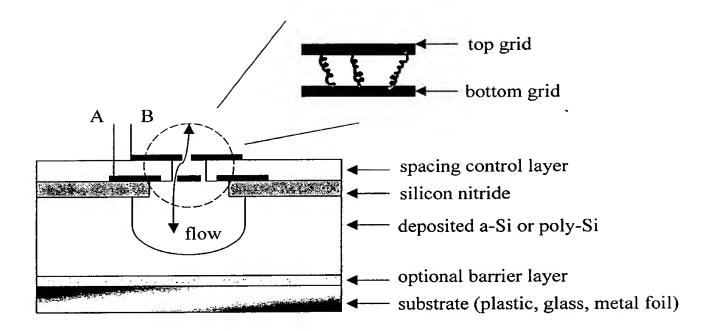






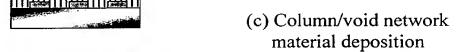




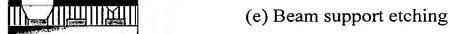


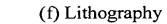


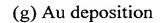












(h) Column/void network material etching